

## SN74LV04A Hex Inverters

### 1 Features

- 2-V to 5.5-V  $V_{CC}$  Operation
- Max  $t_{pd}$  of 6.5 ns at 5 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Typical  $V_{OLP}$  (Output Ground Bounce) < 0.8 V at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot) > 2.3 V at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model
  - 200-V Machine Model
  - 1000-V Charged-Device Model

### 2 Applications

- Power Sub-Station Controls
- Ethernet Switches
- Flow Meters
- I/O Modules; Digital PLC/DCS Inputs
- Servers
- Tests and Measurement

### 3 Description

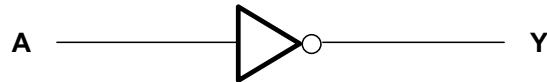
This hex inverter is designed for 2-V to 5.5-V  $V_{CC}$  operation. The SN74LV04A device contains six independent inverters. This device perform the Boolean function  $Y = \bar{A}$ .

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74LV04A	TVSOP (14)	3.60 mm x 4.40 mm
	SOIC (14)	8.65 mm x 3.91 mm
	VQFN (14)	3.50 mm x 3.50 mm
	SSOP (14)	6.20 mm x 5.30 mm
	TSSOP (14)	5.00 mm x 4.40 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### 4 Simplified Schematic



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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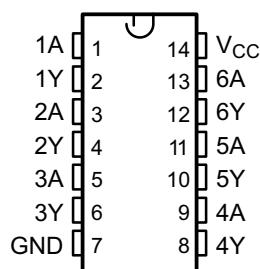
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## 5 Revision History

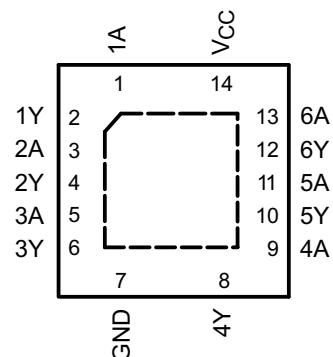
Changes from Revision J (April 2005) to Revision K	Page
• Added <i>Applications</i> , <i>Device Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Typical Characteristics</i> , <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section. ....	1
• Deleted <i>Ordering Information</i> table. ....	1
• Changed MAX operating temperature to 125°C in <i>Recommended Operating Conditions</i> table. ....	5

## 6 Pin Configuration and Functions

**SN74LV04A . . . D, DB, DGV, NS,  
OR PW PACKAGE  
(TOP VIEW)**



**SN74LV04A . . . RGY PACKAGE  
(TOP VIEW)**



### Pin Functions

NAME	PIN		TYPE	DESCRIPTION		
	SN74LV04A					
	D, DB, DGV, NS, PW	RGY				
1A	1	1	I	1A Input		
1Y	2	2	O	1Y Output		
2A	3	3	I	2A Input		
2Y	4	4	O	2Y Output		
3A	5	5	I	3A Input		
3Y	6	6	O	3Y Output		
4Y	8	8	O	4Y Output		
4A	9	9	I	4A Input		
5Y	10	10	O	5Y Output		
5A	11	11	I	5A Input		
6Y	12	12	O	6Y Output		
6A	13	13	I	6A Input		
GND	7	7	—	Ground Pin		
V <sub>CC</sub>	14	14	—	Power Pin		

## 7 Specifications

### 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	–0.5	7	V
$V_I$	Input voltage range <sup>(2)</sup>	–0.5	7	V
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	–0.5	7	V
$V_O$	Output voltage range <sup>(2)(3)</sup>	–0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current $V_I < 0$		–20	mA
$I_{OK}$	Output clamp current $V_O < 0$		–50	mA
$I_O$	Continuous output current $V_O = 0$ to $V_{CC}$		±25	mA
	Continuous current through $V_{CC}$ or GND		±50	mA
$T_{stg}$	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 5.5-V maximum.

### 7.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	2000	V
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		2	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5	V <sub>CC</sub> × 0.7	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.7		
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.7		
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.7		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V	0.5	V <sub>CC</sub> × 0.3	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.3		
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.3		
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.3		
V <sub>I</sub>	Input voltage		0	5.5	V
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2 V	–50	μA	mA
		V <sub>CC</sub> = 2.3 V to 2.7 V	–2		
		V <sub>CC</sub> = 3 V to 3.6 V	–6		
		V <sub>CC</sub> = 4.5 V to 5.5 V	–12		
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V	50	μA	mA
		V <sub>CC</sub> = 2.3 V to 2.7 V	2		
		V <sub>CC</sub> = 3 V to 3.6 V	6		
		V <sub>CC</sub> = 4.5 V to 5.5 V	12		
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 2.3 V to 2.7 V	200	ns/V	
		V <sub>CC</sub> = 3 V to 3.6 V	100		
		V <sub>CC</sub> = 4.5 V to 5.5 V	20		
T <sub>A</sub>	Operating free-air temperature		–40	125	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs* (SCBA004).

### 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SN74LV04A						UNIT	
	D	DB	DGV	NS	PW	RGY		
	14 PINS							
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	94.9	107.4	130.4	91.4	122.6	57.6	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	56.3	59.9	53.4	49.0	51.3	70.4	
R <sub>θJB</sub>	Junction-to-board thermal resistance	49.2	54.7	63.5	50.2	64.4	33.6	
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	20.7	21.0	7.3	15.3	6.8	.3.5	
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	48.9	51.2	62.8	49.8	63.8	33.7	
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	—	—	—	—	—	14.1	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

## 7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			−40°C to 85°C		−40°C to 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = −50 µA	2 V to 5.5 V	V <sub>CC</sub> − 0.1			V <sub>CC</sub> − 0.1		V <sub>CC</sub> − 0.1		V
	I <sub>OH</sub> = −2 mA	2.3 V	2			2		2		
	I <sub>OH</sub> = −6 mA	3 V	2.48			2.48		2.48		
	I <sub>OH</sub> = −12 mA	4.5 V	3.8			3.8		3.8		
V <sub>OL</sub>	I <sub>OL</sub> = 50 µA	2 V to 5.5 V		0.1			0.1		0.1	V
	I <sub>OL</sub> = 2 mA	2.3 V		0.4			0.4		0.4	
	I <sub>OL</sub> = 6 mA	3 V		0.44			0.44		0.44	
	I <sub>OL</sub> = 12 mA	4.5 V		0.55			0.55		0.55	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V		±1			±1		±1	µA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V		20			20		20	µA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5 V	0		5			5		5	µA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		2.3						pF
		5 V		2.3						

## 7.6 Switching Characteristics, V<sub>CC</sub> = 2.5 V ± 0.2 V

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			−40°C to 85°C		−40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	C <sub>L</sub> = 15 pF	7.1 <sup>(1)</sup>	11.7 <sup>(1)</sup>		1	14	1	15	ns
			C <sub>L</sub> = 50 pF	10	15.5		1	18	1	19	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

## 7.7 Switching Characteristics, V<sub>CC</sub> = 3.3 V ± 0.3 V

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			−40°C to 85°C		−40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	C <sub>L</sub> = 15 pF	5.1 <sup>(1)</sup>	7.1 <sup>(1)</sup>		1	8.5	1	9.5	ns
			C <sub>L</sub> = 50 pF	7.3	10.6		1	12	1	13	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

## 7.8 Switching Characteristics, V<sub>CC</sub> = 5 V ± 0.5 V

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			−40°C to 85°C		−40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	C <sub>L</sub> = 15 pF	3.6 <sup>(1)</sup>	5.5 <sup>(1)</sup>		1	6.5	1	7.5	ns
			C <sub>L</sub> = 50 pF	5.1	7.5		1	8.5	1	9.5	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

## 7.9 Noise Characteristics<sup>(1)</sup>

$V_{CC} = 3.3 \text{ V}$ ,  $C_L = 50 \text{ pF}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER	SN74LV04A			UNIT
	MIN	TYP	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic $V_{OL}$		0.3	0.8	V
$V_{OL(V)}$ Quiet output, minimum dynamic $V_{OL}$		-0.1	-0.8	V
$V_{OH(V)}$ Quiet output, minimum dynamic $V_{OH}$		3.1		V
$V_{IH(D)}$ High-level dynamic input voltage	2.31			V
$V_{IL(D)}$ Low-level dynamic input voltage		0.99		V

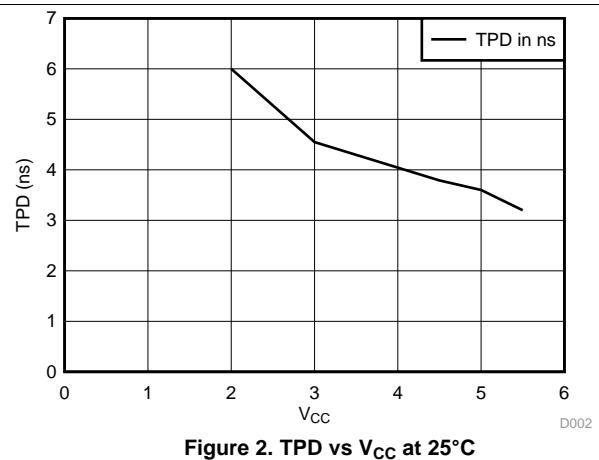
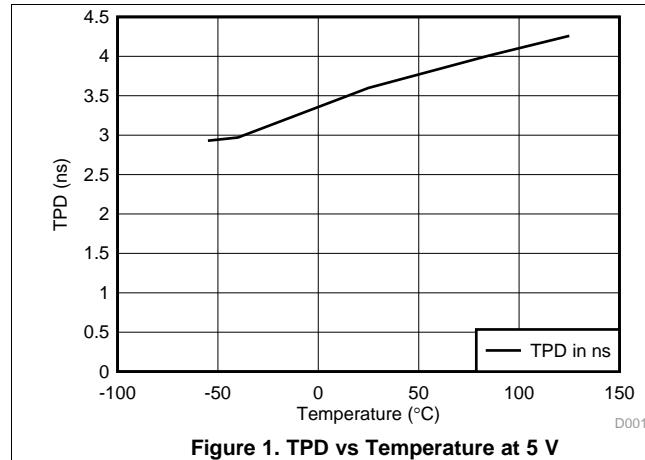
(1) Characteristics are for surface-mount packages only.

## 7.10 Operating Characteristics

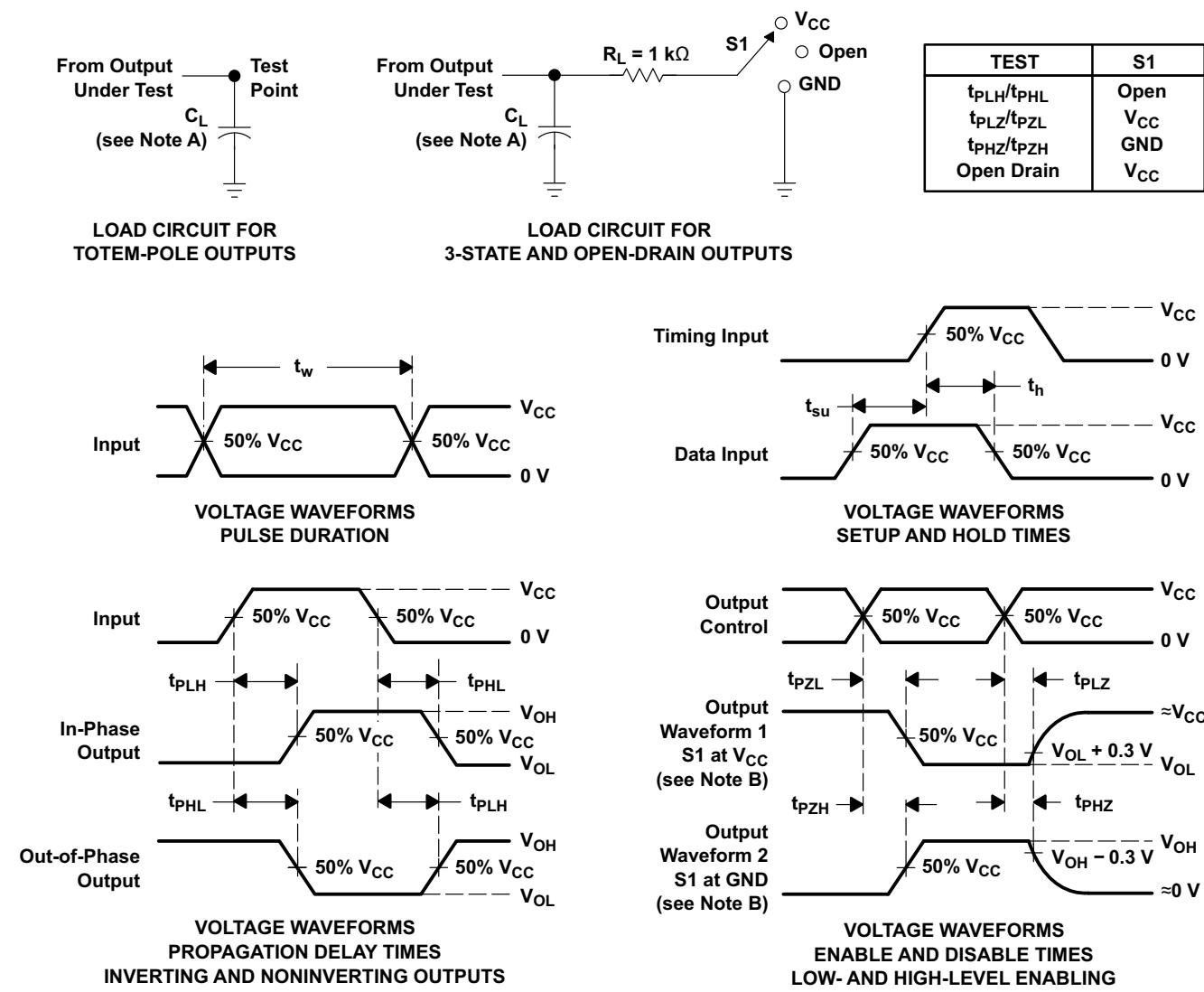
$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC}$	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	$C_L = 50 \text{ pF}$ , $f = 10 \text{ MHz}$	3.3 V	9.6	pF
		5 V	11.4	

## 7.11 Typical Characteristics



## 8 Parameter Measurement Information



NOTES:

- $C_L$  includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 3$  ns,  $t_f \leq 3$  ns.
- The outputs are measured one at a time, with one input transition per measurement.
- $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
- All parameters and waveforms are not applicable to all devices.

**Figure 3. Load Circuit and Voltage Waveforms**

## 9 Detailed Description

### 9.1 Overview

These hex inverters are designed for 2-V to 5.5-V  $V_{CC}$  operation. The SN74LV04A devices contain six independent inverters. These devices perform the Boolean function  $Y = \bar{A}$ .

These devices are fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

The inputs are high impedance when  $V_{CC} = 0V$ .

### 9.2 Functional Block Diagram

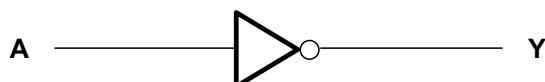


Figure 4. Logic Diagram Each Inverter (Positive Logic)

### 9.3 Feature Description

- Wide operating voltage range
  - Operates from 2 V to 5.5 V
- Allows down-voltage translation
  - Inputs accept voltages to 5.5 V
- $I_{off}$  feature
  - Supports Live Insertion, Partial Power DownMode, and Back Drive Protection

### 9.4 Device Functional Modes

Table 1. Function Table  
(Each Inverter)

INPUT A	OUTPUT Y
H	L
L	H

## 10 Application and Implementation

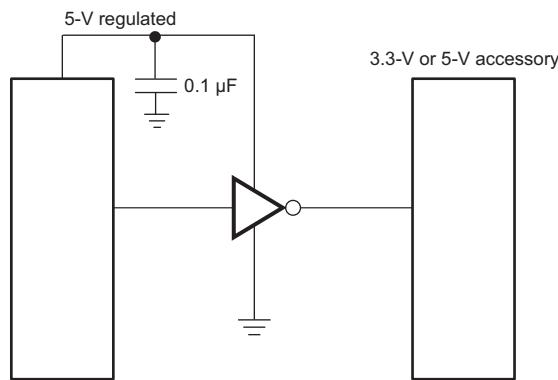
### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 10.1 Application Information

SN74LV04A is a low-drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The inputs can accept voltages to 5.5 V at any valid  $V_{CC}$  making it ideal for down translation.

### 10.2 Typical Application



**Figure 5. Typical Application Schematic**

#### 10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

#### 10.2.2 Detailed Design Procedure

1. Recommended Input Conditions
  - For rise time and fall time specifications, see  $\Delta t/\Delta V$  in the *Recommended Operating Conditions* table.
  - For specified High and low levels, see  $V_{IH}$  and  $V_{IL}$  in the *Recommended Operating Conditions* table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .
2. Recommend Output Conditions
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.
  - Outputs should not be pulled above  $V_{CC}$ .

## Typical Application (continued)

### 10.2.3 Application Curves

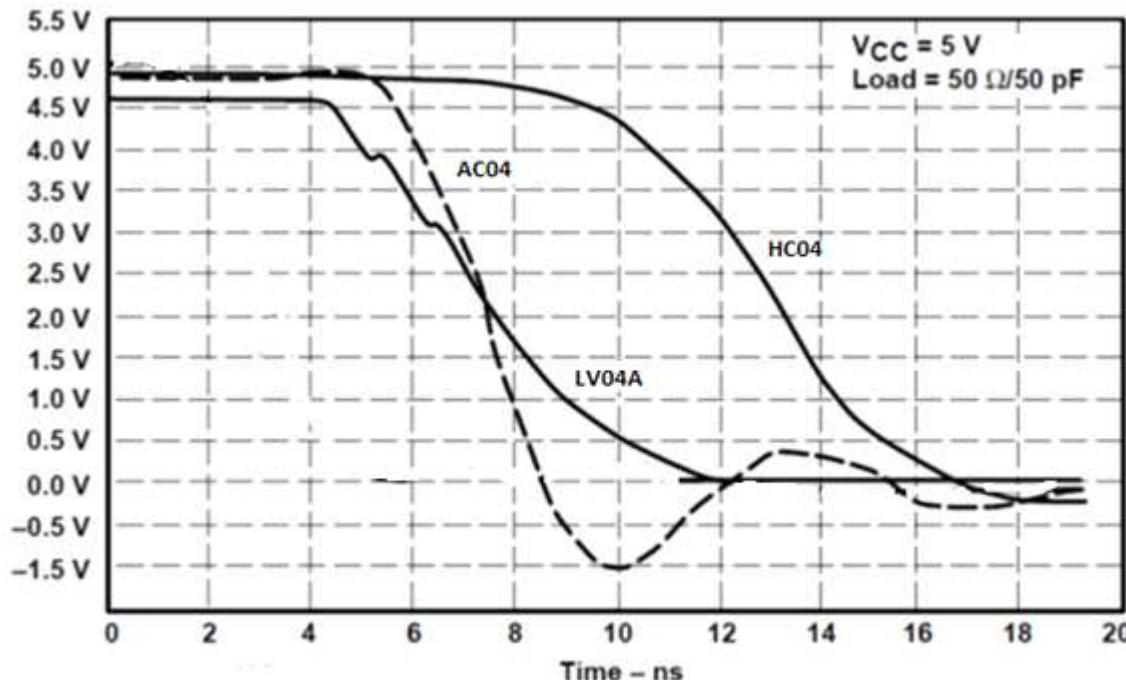


Figure 6. Typical Application Curve

## 11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the *Recommended Operating Conditions* table.

Each V<sub>CC</sub> pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu$ F is recommended. If there are multiple V<sub>CC</sub> pins, 0.01  $\mu$ F or 0.022  $\mu$ F is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu$ F and 1  $\mu$ F are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

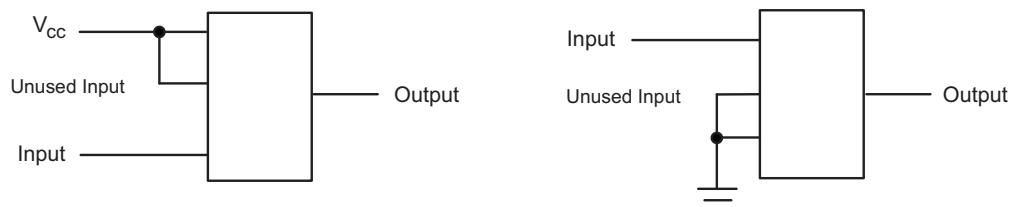
## 12 Layout

### 12.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Figure 7](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$ , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

### 12.2 Layout Example



**Figure 7. Layout Diagram**

## 13 Device and Documentation Support

### 13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 2. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
<a href="#">SN74LV04A</a>	<a href="#">Click here</a>				

### 13.2 Trademarks

All trademarks are the property of their respective owners.

### 13.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 13.4 Glossary

#### SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

## 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74LV04AD</a>	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-40 to 125	LV04A
<a href="#">SN74LV04ADBR</a>	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04ADBR.A	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
<a href="#">SN74LV04ADGVR</a>	Active	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04ADGVR.A	Active	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04ADGVRE4	Active	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
<a href="#">SN74LV04ADR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04ADR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04ADR.B	Active	Production	SOIC (D)   14	2500   LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04ADRG4	Active	Production	SOIC (D)   14	2500   null	No	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04ADRG4	Active	Production	SOIC (D)   14	2500   null	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04ADRG4.A	Active	Production	SOIC (D)   14	2500   null	No	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04ADRG4.A	Active	Production	SOIC (D)   14	2500   null	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
<a href="#">SN74LV04ANSR</a>	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV04A
SN74LV04ANSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV04A
<a href="#">SN74LV04APWR</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04APWR.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04APWR.B	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
<a href="#">SN74LV04APWRG4</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04APWRG4.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
SN74LV04APWRG4.B	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV04A
<a href="#">SN74LV04APWT</a>	Obsolete	Production	TSSOP (PW)   14	-	-	Call TI	Call TI	-40 to 125	LV04A
<a href="#">SN74LV04ARGYR</a>	Active	Production	VQFN (RGY)   14	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LV04A
SN74LV04ARGYR.A	Active	Production	VQFN (RGY)   14	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LV04A

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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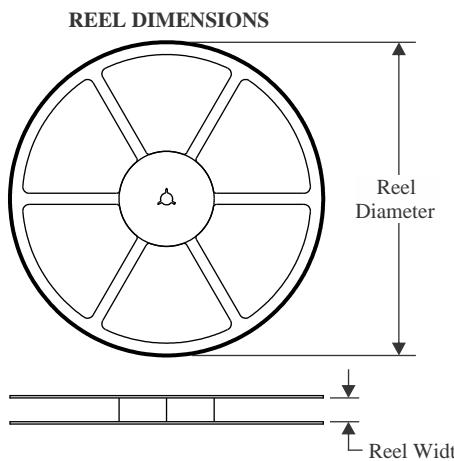
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN74LV04A :**

- Automotive : [SN74LV04A-Q1](#)
- Enhanced Product : [SN74LV04A-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

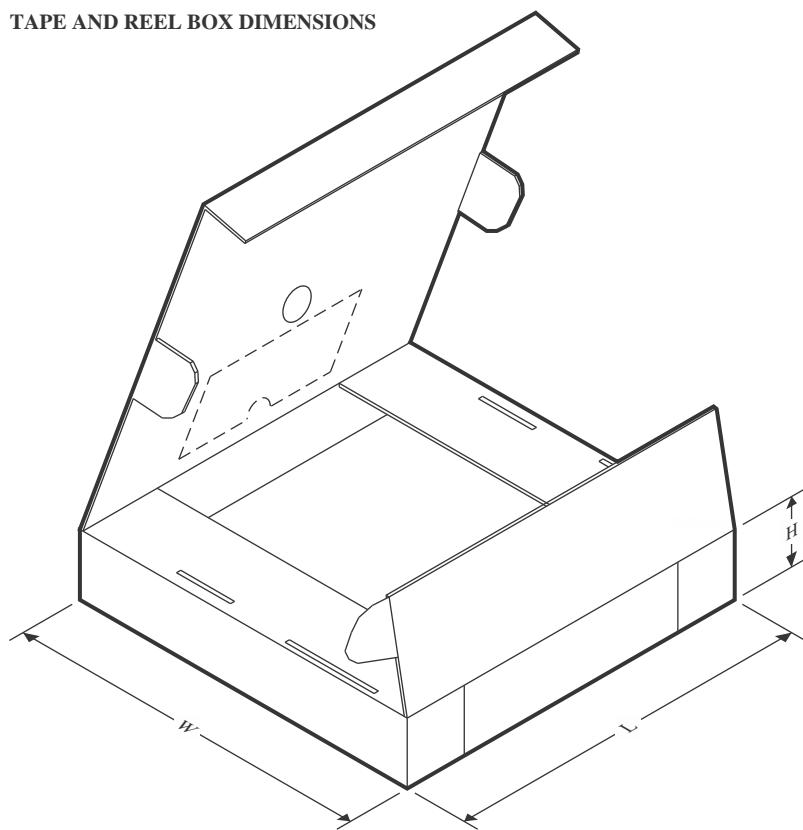
**TAPE AND REEL INFORMATION**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV04ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV04ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV04ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV04ANSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LV04APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV04APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV04ARGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


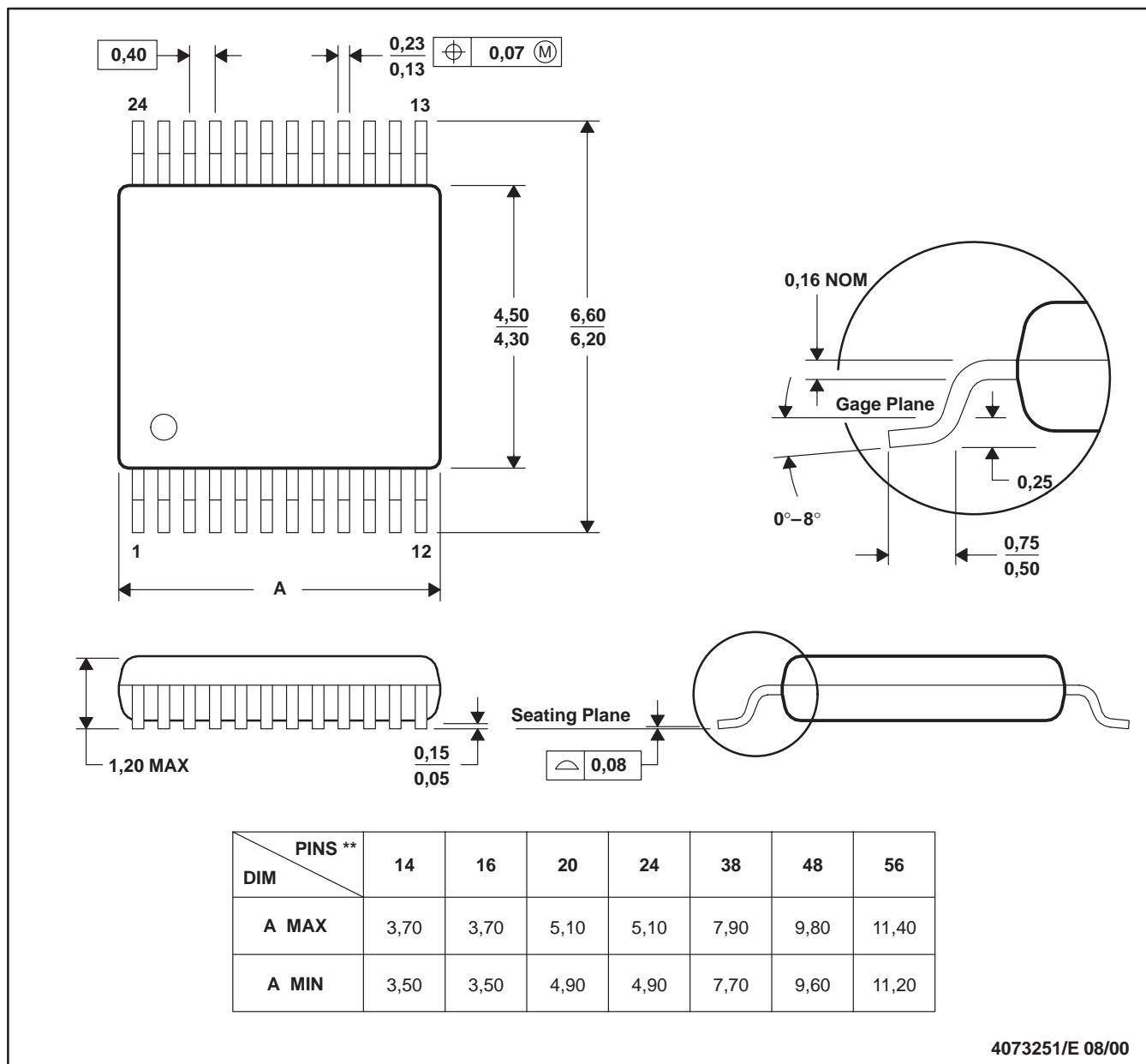
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV04ADBR	SSOP	DB	14	2000	353.0	353.0	32.0
SN74LV04ADGVR	TVSOP	DGV	14	2000	353.0	353.0	32.0
SN74LV04ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LV04ANSR	SOP	NS	14	2000	353.0	353.0	32.0
SN74LV04APWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LV04APWRG4	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74LV04ARGYR	VQFN	RGY	14	3000	353.0	353.0	32.0

## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

24 PINS SHOWN

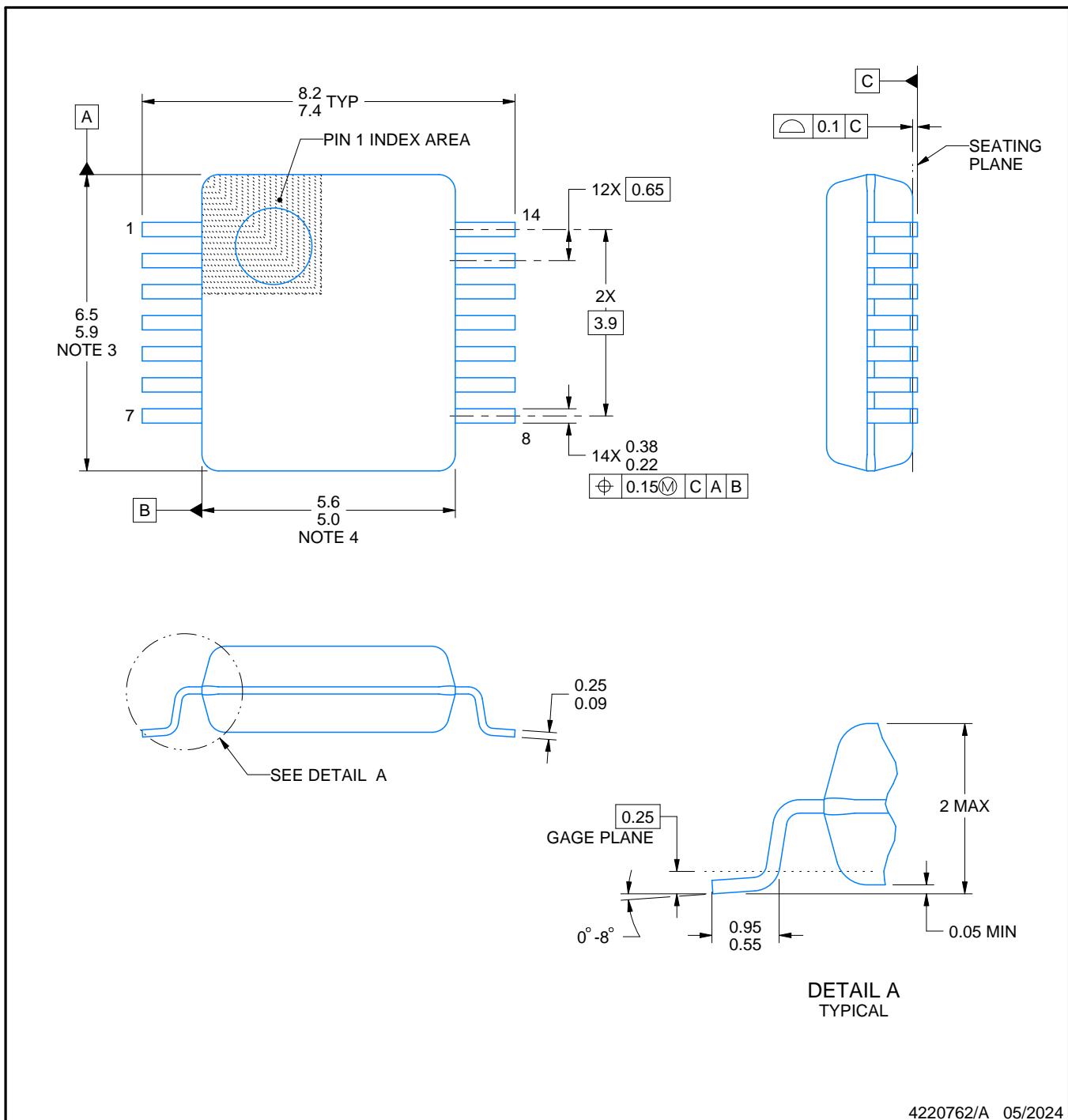


NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



### NOTES:

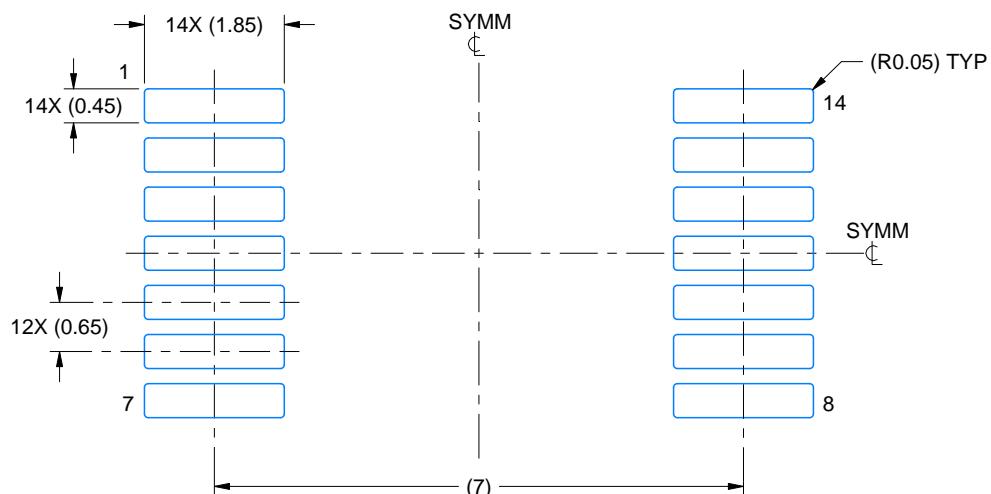
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

## EXAMPLE BOARD LAYOUT

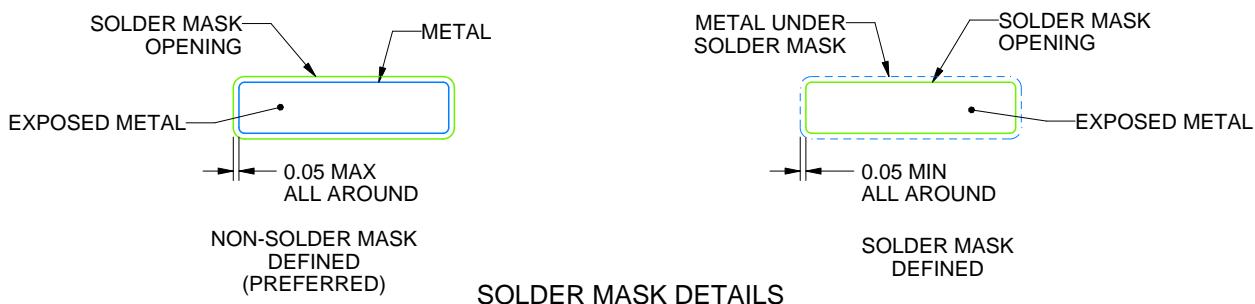
**DB0014A**

## SSOP - 2 mm max height

## SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220762/A 05/2024

#### NOTES: (continued)

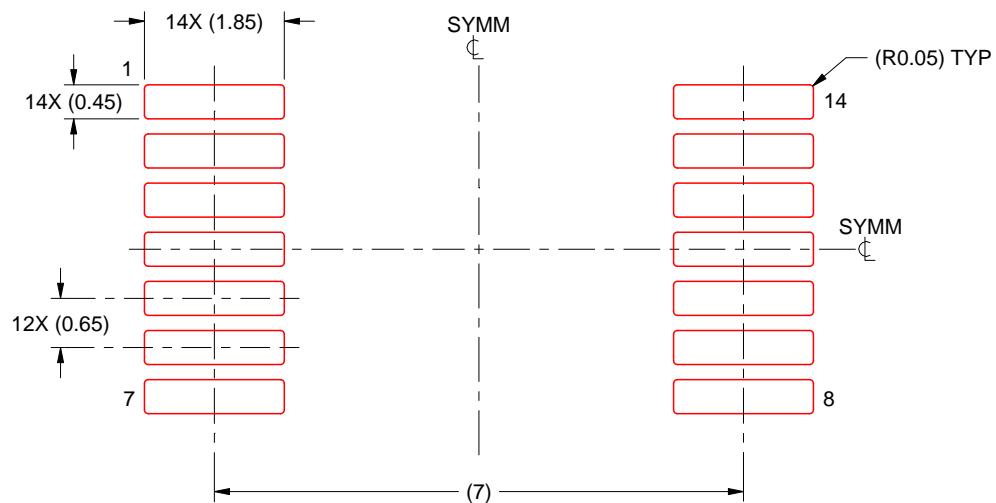
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

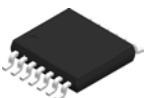
4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

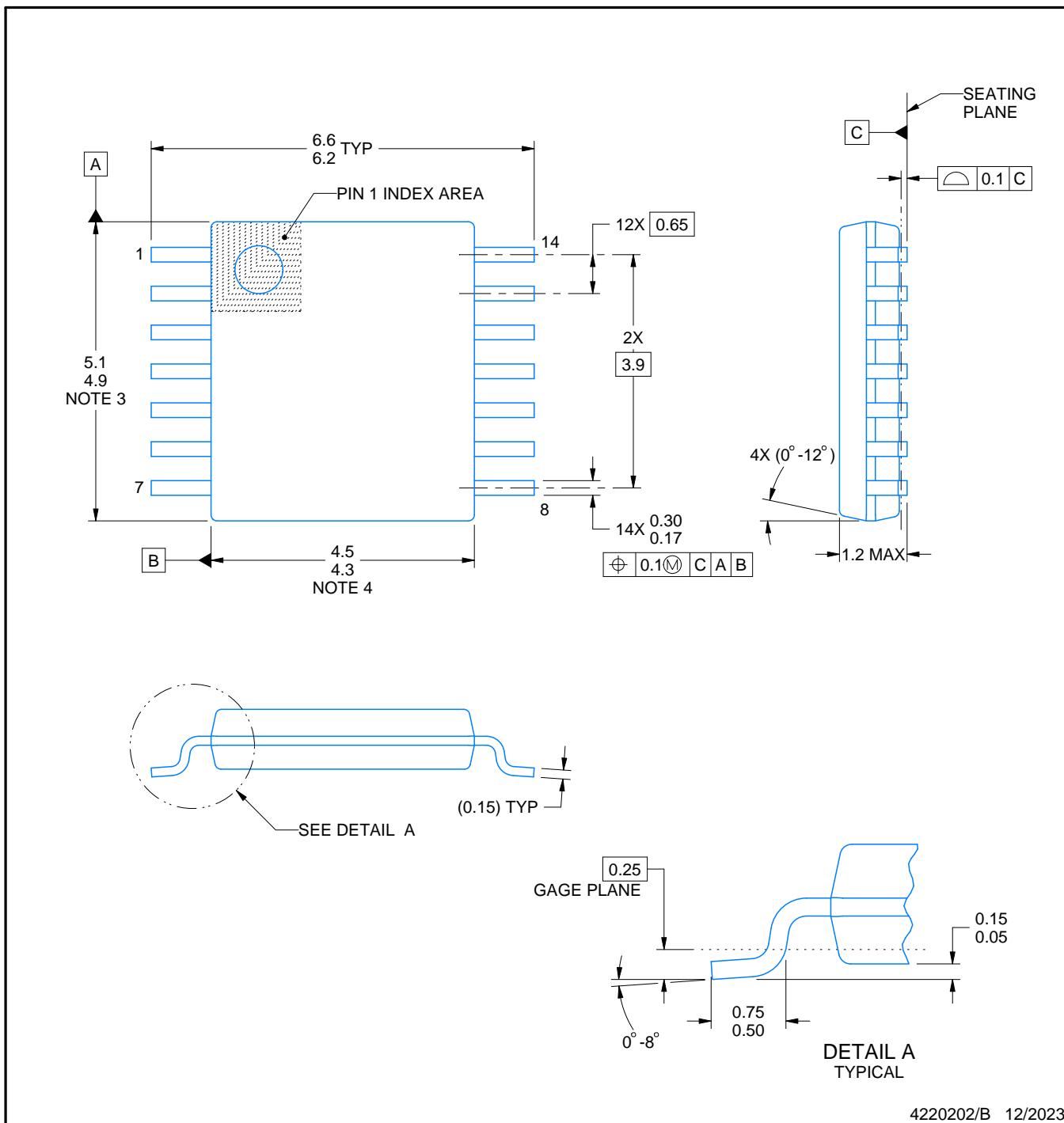
# PACKAGE OUTLINE

PW0014A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



## NOTES:

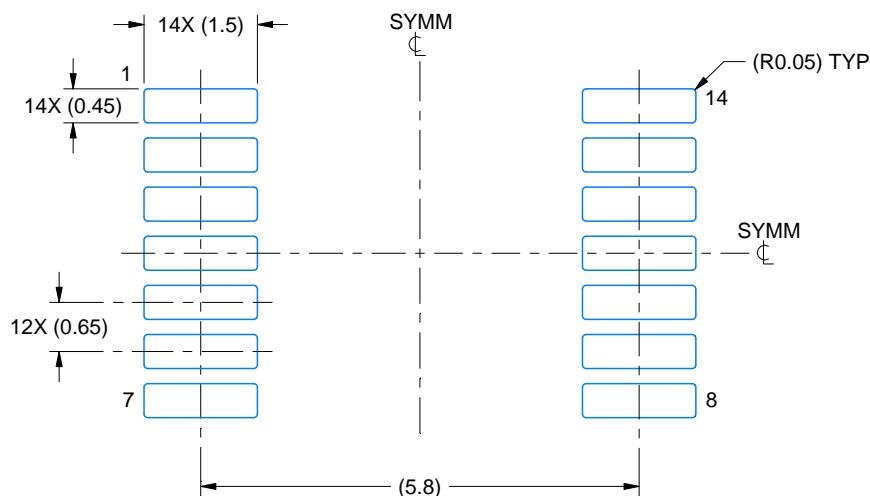
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

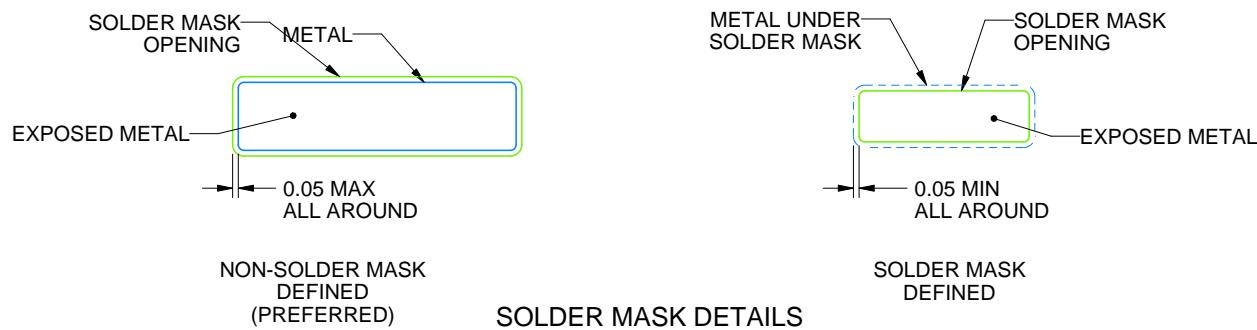
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

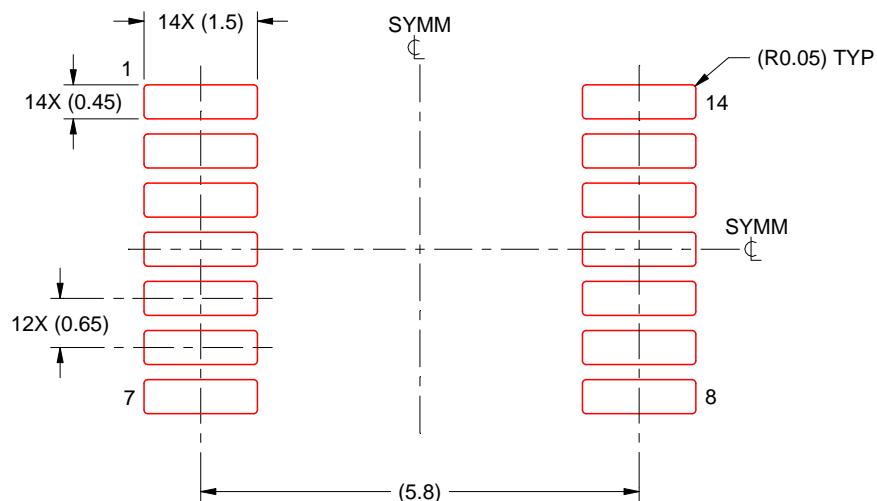
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

**PW0014A**

## **TSSOP - 1.2 mm max height**

## SMALL OUTLINE PACKAGE



**SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X**

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

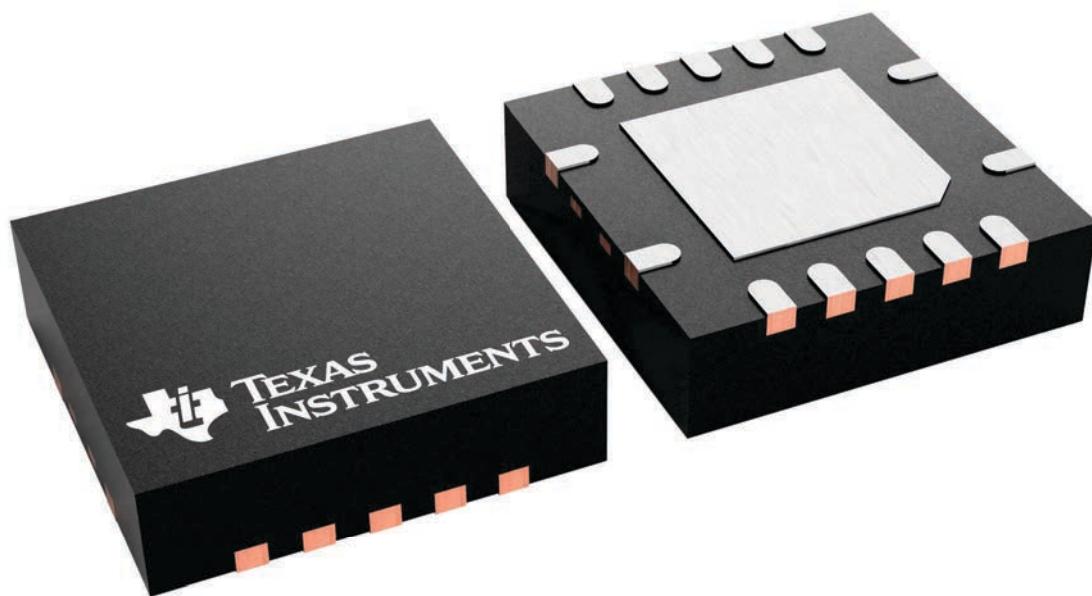
**RGY 14**

**VQFN - 1 mm max height**

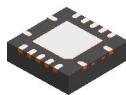
**3.5 x 3.5, 0.5 mm pitch**

**PLASTIC QUAD FLATPACK - NO LEAD**

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



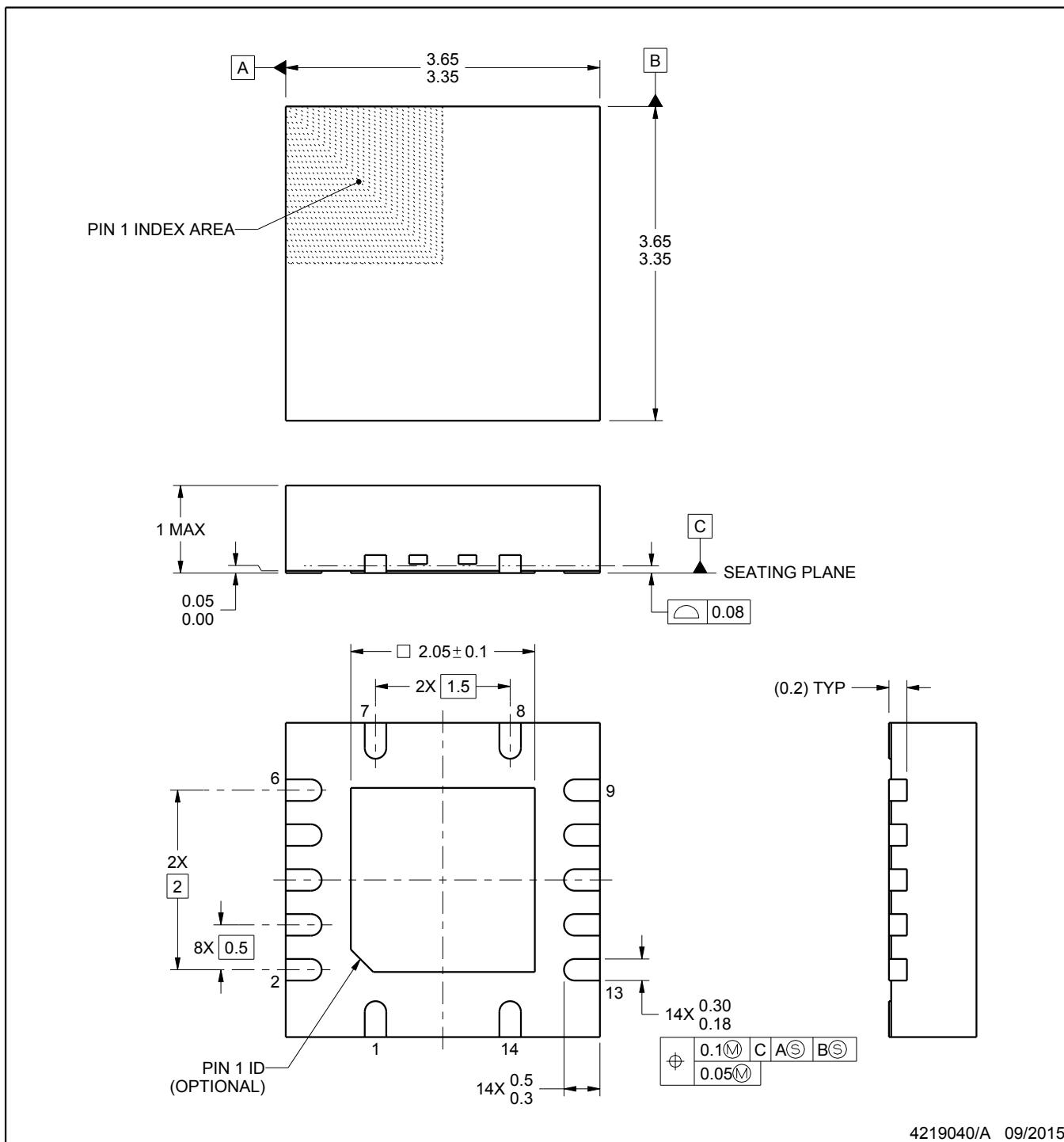
4231541/A



# PACKAGE OUTLINE

## VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



### NOTES:

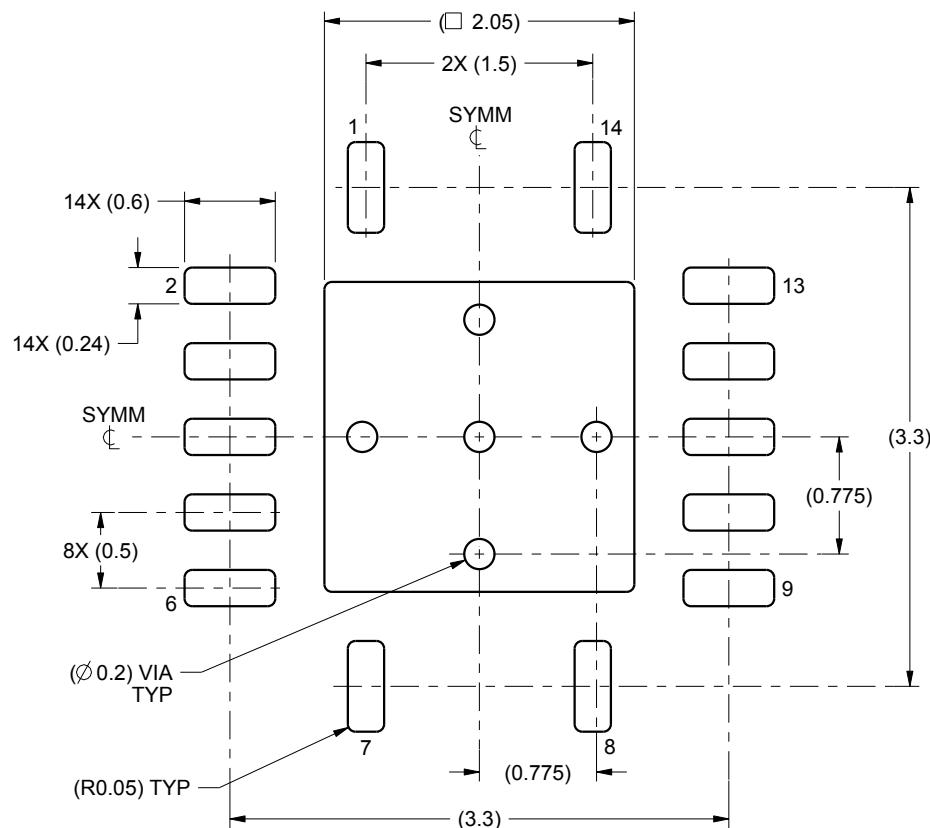
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

## EXAMPLE BOARD LAYOUT

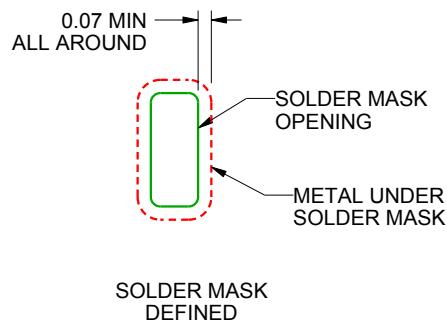
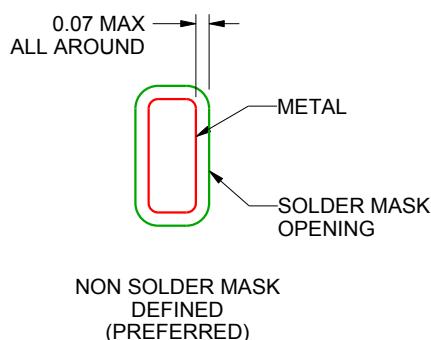
**RGY0014A**

## VQFN - 1 mm max height

#### PLASTIC QUAD FLATPACK - NO LEAD



## LAND PATTERN EXAMPLE



## SOLDER MASK DETAILS

4219040/A 09/2015

#### NOTES: (continued)

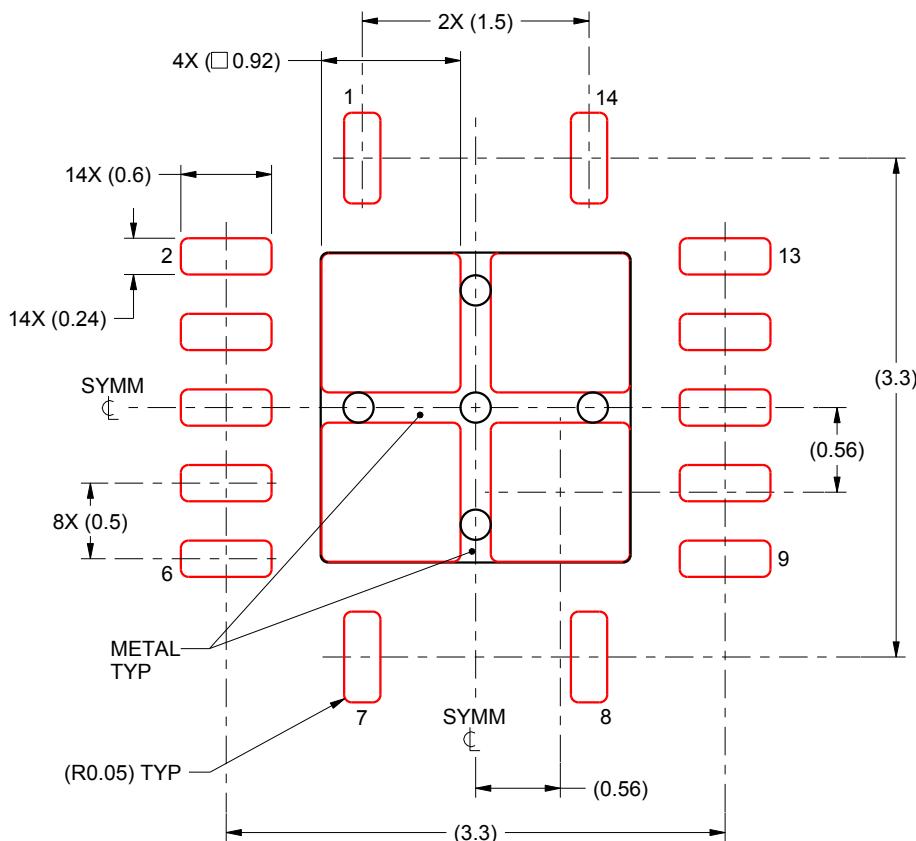
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

RGY0014A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
80% PRINTED SOLDER COVERAGE BY AREA  
SCALE:20X

4219040/A 09/2015

NOTES: (continued)

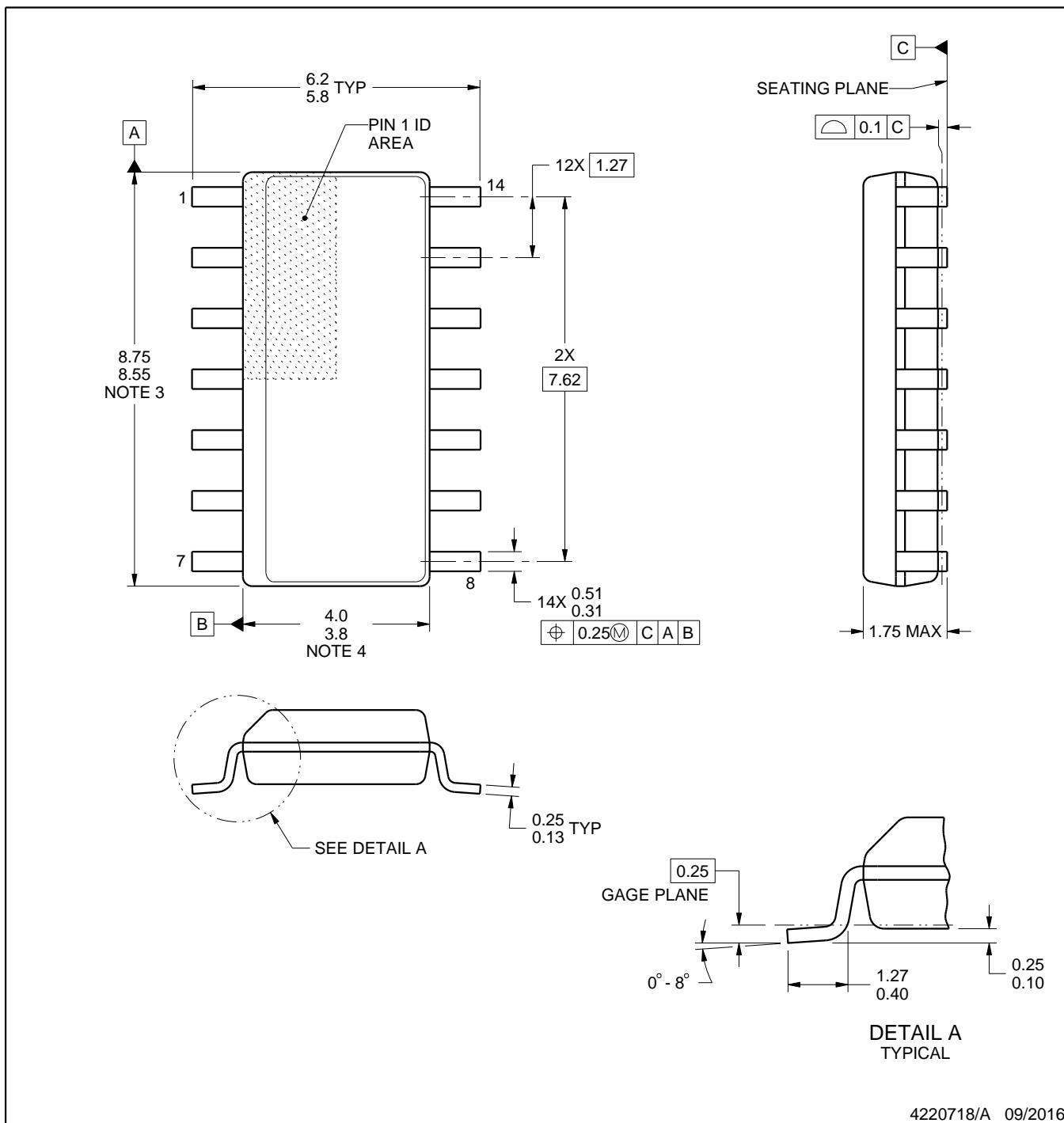
5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

# PACKAGE OUTLINE

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

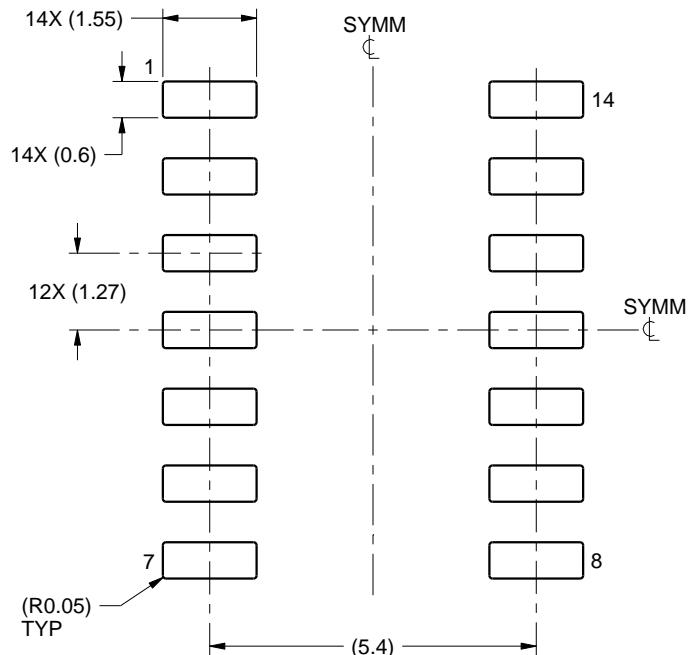
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

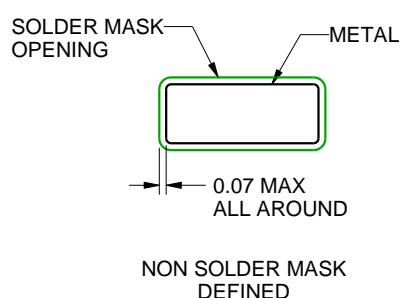
D0014A

SOIC - 1.75 mm max height

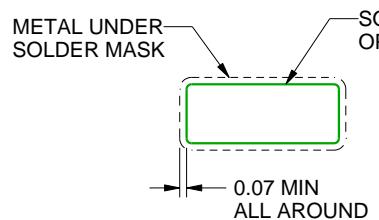
SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



NON SOLDER MASK  
DEFINED



SOLDER MASK  
DEFINED

SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

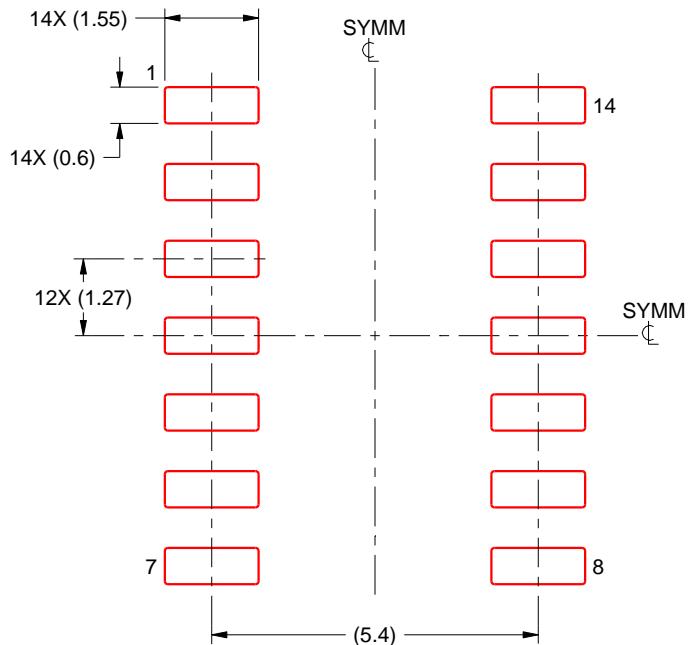
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

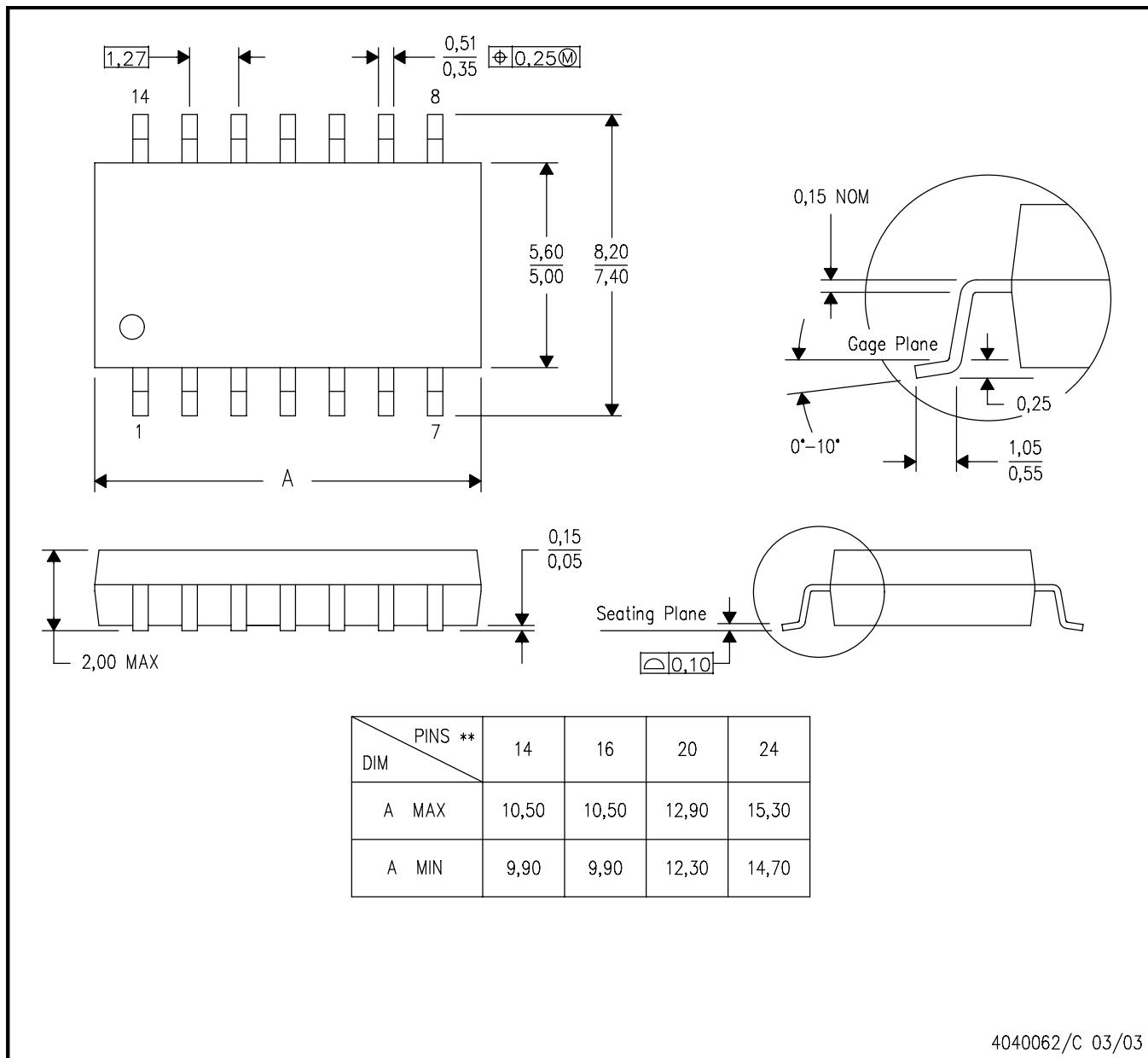
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

## PLASTIC SMALL-OUTLINE PACKAGE

**14-PINS SHOWN**



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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